Dual P-channel MOSFET

ELM14815AA-N

■General description

ELM14815AA-N uses advanced trench technology to provide excellent Rds(on) and low gate charge. Internal ESD protection is included.

Features

- Vds=-30V
- Id=-8A (Vgs=-20V)
- Rds(on) $< 18m \Omega$ (Vgs=-20V)
- Rds(on) $< 20 \text{m} \Omega$ (Vgs=-10V)
- ESD Rating: 2000V HBM

■ Maximum absolute ratings

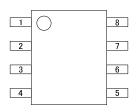
Parameter		Symbol	Limit	Unit	Note
Drain-source voltage		Vds	-30	V	
Gate-source voltage		Vgs	±25	V	
Continuous drain current	Ta=25℃	1.1	-8.0	Δ.	1
	Ta=70°C	Id	-6.9	A	1
Pulsed drain current		Idm	-40	А	2
Power dissipation	Ta=25℃	DЧ	2.00	NA.	1
	Ta=70°C	Pd	1.44	W	
Junction and storage temperature range		Tj, Tstg	-55 to 150	$^{\circ}$ C	

■Thermal characteristics

Parameter		Symbol	Тур.	Max.	Unit	Note	
Maximum junction-to-ambient	t≤10s	Rθja	50.0	62.5	°C/W	1	
Maximum junction-to-ambient	Steady-state	Koja	73.0	110.0	°C/W	1	
Maximum junction-to-lead	Steady-state	Rθjl	31.0	40.0	°C/W	3	

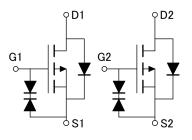
■Pin configuration

SOP-8 (TOP VIEW)



Pin No.	Pin name
1	SOURCE2
2	GATE2
3	SOURCE1
4	GATE1
5	DRAIN1
6	DRAIN1
7	DRAIN2
8	DRAIN2

■ Circuit



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■ Electrical characteristics

Ta=25°C

Parameter	Symbol	Condition		Min.	Тур.	Max.	Unit
STATIC PARAMETERS							
Drain-source breakdown voltage	BVdss	$Id=-250 \mu A$, $Vgs=0V$		-30			V
Zero gate voltage drain current	Idss	Vds=-24V				-1] _^
		Vgs=0V	Tj=55℃			-5	μΑ
Gate-body leakage current	Igss	$Vds=0V$, $Vgs=\pm 25$			±1	μΑ	
Gate threshold voltage	Vgs(th)	Vds=Vgs, Id=-250	-1.0	-2.8	-3.0	V	
On state drain current	Id(on)	Vgs=-10V, Vds=-	-40			А	
Static drain-source on-resistance	Rds(on)	Vgs=-20V			14.1	18.0	mΩ
		Id=-8A	Tj=125℃		19.0	24.0	
		Vgs=-10V, Id=-8A	١		16.2	20.0	$m\Omega$
		Vgs=-4.5V, Id=-5A			37		m Ω
Forward transconductance	Gfs	Vds=-5V, Id=-8A			15		S
Diode forward voltage	Vsd	Is=-1A, Vgs=0V				-1	V
Max. body-diode continuous current	Is					-2.6	Α
DYNAMIC PARAMETERS							
Input capacitance	Ciss	Vgs=0V, Vds=-15V, f=1MHz			2330	2900	рF
Output capacitance	Coss				480		рF
Reverse transfer capacitance	Crss				320		рF
Gate resistance	Rg	Vgs=0V, Vds=0V, f=1MHz			6.8	10.0	Ω
SWITCHING PARAMETERS							
Total gate charge	Qg	Vgs=-10V, Vds=-15V Id=-8A			41	52	nC
Gate-source charge	Qgs				10		nC
Gate-drain charge	Qgd				12		nC
Turn-on delay time	td(on)				13.0		ns
Turn-on rise time	tr	Vgs=-10V, Vds=-15V Rl=1.8Ω, Rgen=3Ω			12.0		ns
Turn-off delay time	td(off)				51.0		ns
Turn-off fall time	tf				30.5		ns
Body diode reverse recovery time	trr	If=-8A, dl/dt=100A/ μ s			28.0	35.0	ns
Body diode reverse recovery charge	Qrr	If= $-8A$, dl/dt= $100A/\mu$ s			20.5		пC

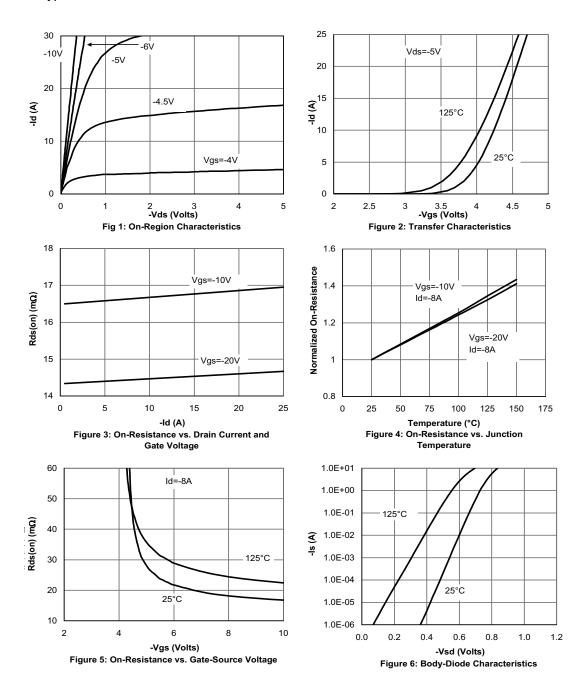
NOTE:

- 1. The value of $R\theta$ ja is measured with the device mounted on 1in^2 FR-4 board of 2oz. Copper, in still air environment with Ta=25°C. The value in any given applications depends on the user's specific board design, The current rating is based on the $t \leq 10s$ themal resistance rating.
- 2. Repetitive rating, pulse width limited by junction temperature.
- 3. The $R\theta$ is the sum of the thermal impedance from junction to lead $R\theta$ and lead to ambient.
- 4. The static characteristics in Figures 1 to 6 are obtained using 80 μs pulses, duty cycle 0.5%max.
- 5. These tests are performed with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with Ta=25°C. The SOA curve provides a single pulse rating.

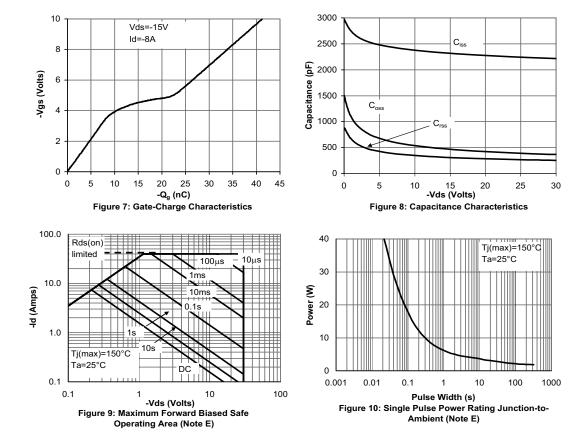


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■ Typical electrical and thermal characteristics



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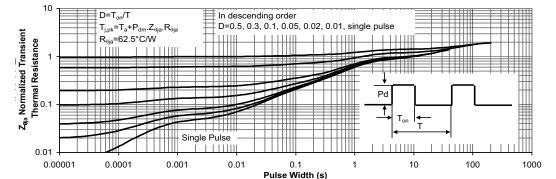


Figure 11: Normalized Maximum Transient Thermal Impedance